

# Bill of Materials

TI DESIGNS  
 Part #: PMP1967  
 Literature #

DESIGNATOR	QUANTITY	VALUE	DESCRIPTION	MANUFACTURER	PART NUMBER	SIZE
C1	1	1000pF	Capacitor, Ceramic, 1000pF, 16V, X7R, 10%, 0402	Std	Std	0402
C12, C14	2	1uF	Capacitor, Ceramic, 1uF, 6.3V, X5R, 10%, 0402	Std	Std	0402
C16, C17	2	Open	Capacitor, Ceramic, Open, 0402	Std	Std	0402
C2, C5	2	22uF	Capacitor, Ceramic, 22uF, 16V, X5R, 20%, 1210	Std	Std	1210
C3, C4	2	33uF	Capacitor, POSCAP, 33uF, 16V, 1.4A, 0.070 Ohms, 20%, 7343	Sanyo	16TQC33M	7343(D)
C6, C7	2	0.1uF	Capacitor, Ceramic, 0.1uF, 16V, X7R, 10%, 0402	Std	Std	0402
C8, C11, C13, C15	4	10uF	Capacitor, Ceramic, 10uF, 6.3V, X5R, 10%, 0805	Std	Std	0805
C9, C10	2	330uF	Capacitor, POSCAP, 330uF, 6.3V, 0.010 Ohms, 20%, 7343	Sanyo	6TPD330M	7343
J1, J2, J3	3	PTC36SAAN	Header, 2-pin, 100mil spacing, (36-pin strip)	Sullins	PTC36SAAN	0.100 inch x 2
J4, J5, J6	3	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	OST	ED1514	0.27 x 0.25 inch
L1, L2	2	4.7uH	Inductor, SMT, 4.7uH, 6.5A, 0.0303 Ohms	Vishay Dale	IHLP2525EZER4R7M01	0.255 x 0.270
Q1, Q2, Q3, Q4	4	FDM6296	MOSFET, N-Ch, 30V, 10A, 0.015 Ohms, MicroFet	Fairchild	FDM6296	PWRPAK 1212
R1, R2	2	0	Resistor, Chip, 0.0 Ohms, 0603	Std	Std	0603
R3	1	9.31K	Resistor, Chip, 9.31K Ohms, 1%, 0402	Std	Std	0402
R4	1	10.7K	Resistor, Chip, 10.7K Ohms, 1%, 0402	Std	Std	0402
R5	1	5.1	Resistor, Chip, 5.1 Ohms, 5%, 0402	Std	Std	0402
R6	1	0	Resistor, Chip, 0.0 Ohms, 0402	Std	Std	0402
R7, R8, R9, R10	4	10K	Resistor, Chip, 10K Ohms, 1%, 0402	Std	Std	0402
TP1, TP2, TP9, TP10	4	5001	Test Point, Black, Thru Hole Color Keyed	Keystone	5001	0.100 x 0.100 inch
TP3, TP4, TP5, TP6, TP7, TP8	6	5000	Test Point, Red, Thru Hole Color Keyed	Keystone	5000	0.100 x 0.100 inch
U1	1	TPS51120RHB	IC, Dual Synchronous PWM Controller, QFN	TI	TPS51120RHB	QFN32

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